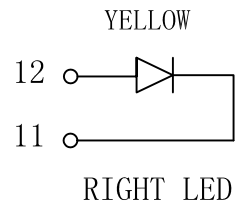
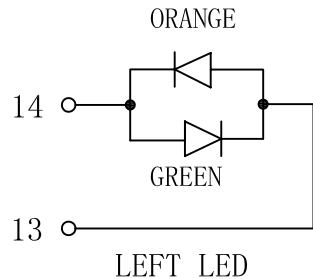
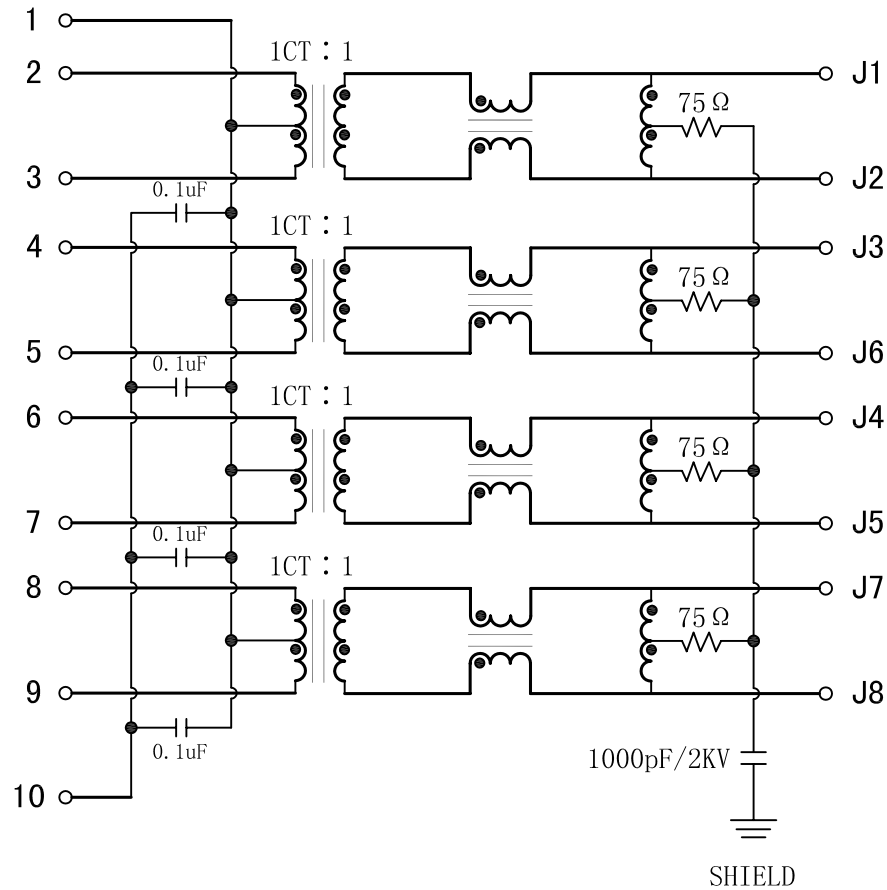


# Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		12/12/2009	TOM



## Electrical Specifications:

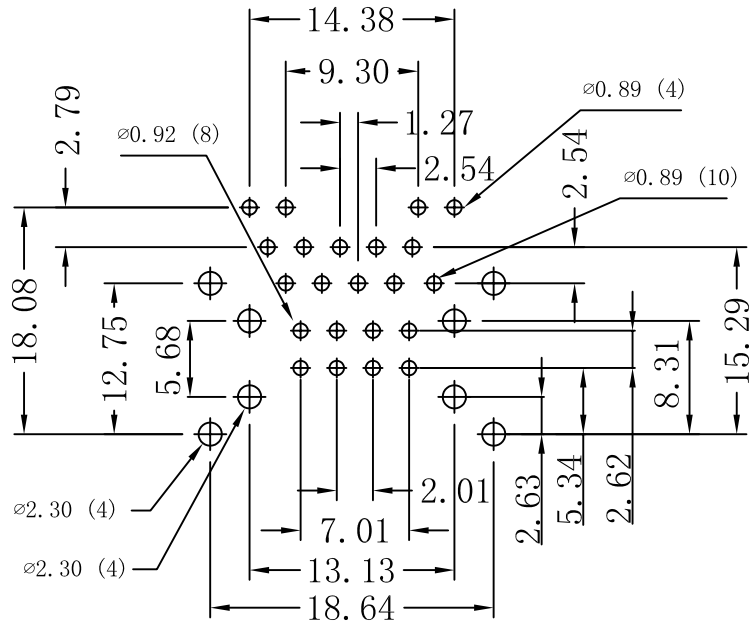
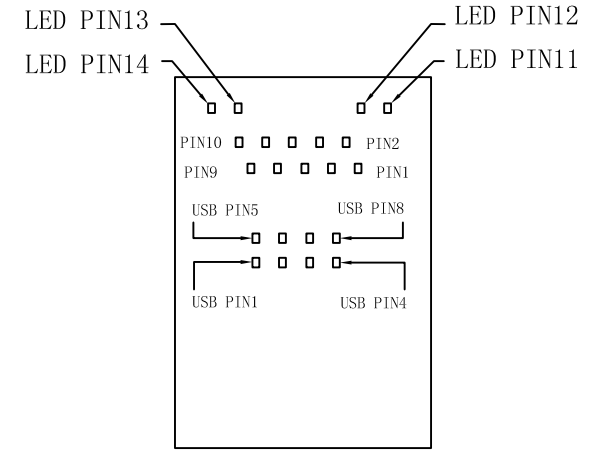
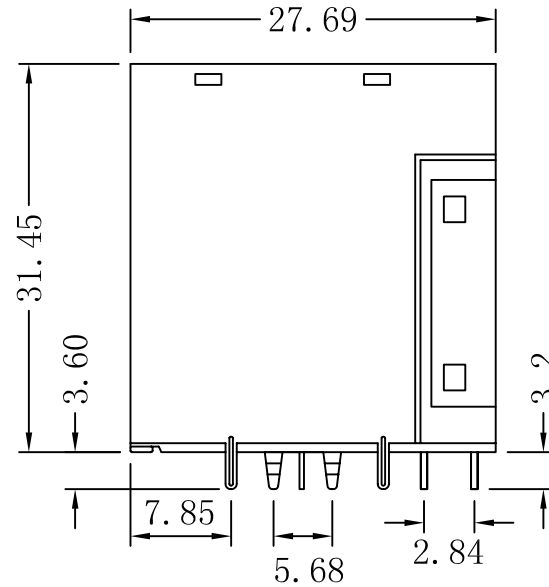
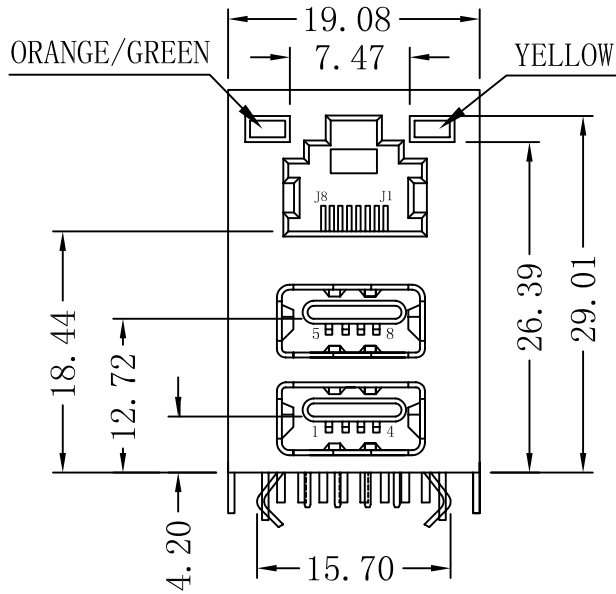
TEST NOTES (25±5°C)

- TR: (100KHz, 0.1V):  
TX=1CT : 1 ±2%      RX=1CT : 1 ±2%
- LX (100KHz, 100mV, 8mA, DC Bias):  
350uH MIN
- HIPOT: 1500VAC FOR 60 SECONDS
- INSERTION LOSS:  
-1.0dB MAX @ 1.0MHz TO 100MHz
- RETURN LOSS:  
-18dB MIN @ 1MHz TO 30MHz  
-16dB MIN @ 30MHz TO 60MHz  
-12dB MIN @ 60MHz TO 80MHz
- CROSS TALK:  
-40dB MIN @ 1MHz TO 10MHz  
-35dB MIN @ 32MHz TO 60MHz  
-30dB MIN @ 60MHz TO 100MHz
- COMMON TO COMMON MODE REJECTION:  
-30dB MIN @ 1MHz TO 50MHz  
-20dB MIN @ 50MHz TO 150MHz
- OPERATING TEMPERATURE: 0°C ~ 70°C.

X:X	±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	±0.20	CHKD:	Title: RJ45 10/100/1000BASE-TX JACK/ Dual USB Combo	
X:XXX	±0.10	DR: TOM	PART NO. : LPJU5202BONL	
ANGLES	±1°	UNIT: mm		
	SCALE: 2/1	SHEET: 1/2	REV: A	DWG NO. :

# Mechanical :

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		12/12/2009	TOM



SUGGESTED PCB LAYOUT (TOP VIEW)

## NOTES:

1. Designed to support application, such as SOHO (ADSL modems), LAN-on-Motherboard (LOM), hub and Switches.
2. Meets IEEE 802.3 specification
3. Connector Materials:  
Housing: Thermoplastic UL94V-0  
Contact/Shield: Copper alloy  
Shield plating: Nickel  
Contact plating: Gold 6 micro-inches min. In contact area.  
USB Contact plating: Gold flash.
4. Wave solder tip temperature: 265°C Max  
Wave solder tip temperature time: 5 Sec Max



X:X	±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	±0.20	CHKD:	Title: RJ45 10/100/1000BASE-TX JACK/ Dual USB Combo	
X:XXX	±0.10	DR: TOM	PART NO.: LPJU5202BONL	
ANGLES	±1°	UNIT: mm		
	SCALE: 2/1	SHEET: 2/2	REV: A	DWG NO.: